



Prelaminated inlays

Combi



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A range of applications.

LUX-IDent's prepressed inlays are designed specifically with the card manufacturer in mind.

Prelaminated inlays Combi consist of two or even more different chip technologies, offering combinations of HF + LF, HF + HF or LF + LF chips in one card. Even a contact chip module can be embedded if the layout is designed accordingly.

Prelaminated inlays are suitable for use in the production of ISO standard cards. LUX-IDent uses a proprietary manufacturing process to produce its prelaminated inlays. Wire embedding and/or coil winding technologies are used depending on suitability.

Our inlays are very robust and boast unequalled torsion/bending characteristics, extreme durability and optimized read/write performance. The inlays have a completely flat finish and bring numerous benefits to card manufacturers.

Our prelaminated inlay is essentially a semi-finished product, so that the card manufacturer merely needs to collate his printed sheets with the inlay and laminate the "sandwich".

FEATURES

- Very reliable and robust plastic package
- High reading distance optimized to each chip
- Materials: PVC, PETG, PC
- Colour: white or transparent
- Possibility of combining two and more different chip technologies in one prelaminated sheet
- Different sheet formats are available 1×5, 2×5, 3×6, 3×7, 3×8, 3×10, 4×10 up to 640×520 mm, others upon request

Based on specific customer requests, our antenna design allows us to position an antenna on the sheet layout along the embedding of contact chip module without any interference from the RFID antenna. This is what we call the hybrid card, which combines contactless and contact chip technology into one card.

EXAMPLE OF APPLICATIONS

- physical access
- logical access
- public transport
- city card
- student card
- e-purse systems, etc.

AVAILABLE CHIP TECHNOLOGIES

Manufacturer frequency	Chip type
EM Microelectronic	
LF 125 /134.2 kHz	EM4102, EM4200, EM4305, EM4450
NXP	
LF 125 /134.2 kHz	Hitag® 1, Hitag® 2, Hitag® S 256bit, Hitag® S 2048bit
HF 13.56 MHz	MIFARE Ultralight® C, MIFARE Ultralight® EV1, MIFARE Classic® 1K EV1, MIFARE Classic® 4K EV1, MIFARE® DESFire® 256B EV1, MIFARE® DESFire® 2K EV1/EV2, MIFARE® DESFire® 4K EV1/EV2, MIFARE® DESFire® 8K EV1/EV2, MIFARE Plus® SE, MIFARE Plus® S 2K, MIFARE Plus® S 4K, MIFARE Plus® X 2K, MIFARE Plus® X 4K, MIFARE Plus® EV1 2K, MIFARE Plus® EV1 4K I-Code® SLIX NTAG213, NTAG215, NTAG216 SmartMX (JCOP)
Infineon	
HF 13.56 MHz	NRG SLE66R35 1K
Microchip – Atmel	
LF 125 /134.2 kHz	ATA5575M1, ATA5575M2, ATA5577, Q5
LEGIC®	
HF 13.56 MHz	Prime: MIM256, MIM1024 Advant: ATC256-MV410, ATC1024-MV110, ATC1024-MV010, ATC4096-MP311 CTC 4096-MP410, CTC 4096-MM410

Other ICs are available upon request.

